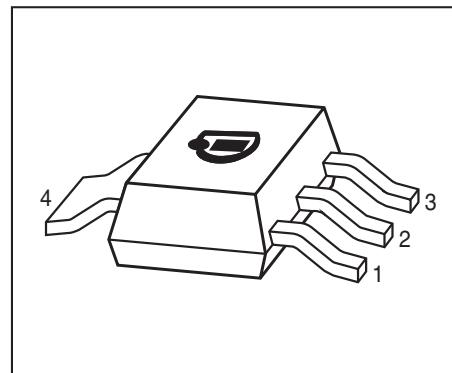


### **PNP Silicon AF Power Transistors**

- For AF driver and output stages
- High collector current
- High current gain
- Low collector-emitter saturation voltage
- Complementary types: BDP947, BDP949  
BDP953 (NPN)
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



Type	Marking	Pin Configuration						Package
BDP948	BDP948	1=B	2=C	3=E	4=C	-	-	SOT223
BDP950	BDP950	1=B	2=C	3=E	4=C	-	-	SOT223
BDP954	BCP954	1=B	2=C	3=E	4=C	-	-	SOT223

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage BDP948	$V_{CEO}$	45	V
BDP950		60	
BDP954		100	
Collector-base voltage BDP948	$V_{CBO}$	45	
BDP950		60	
BDP954		120	
Emitter-base voltage	$V_{EBO}$	5	
Collector current	$I_C$	3	A
Peak collector current, $t_p \leq 10$ ms	$I_{CM}$	5	
Base current	$I_B$	200	mA
Peak base current	$I_{BM}$	500	
Total power dissipation- $T_S \leq 100$ °C	$P_{tot}$	5	W
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{stg}$	-65 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	$R_{thJS}$	$\leq 10$	K/W

<sup>1</sup>Pb-containing package may be available upon special request

<sup>2</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

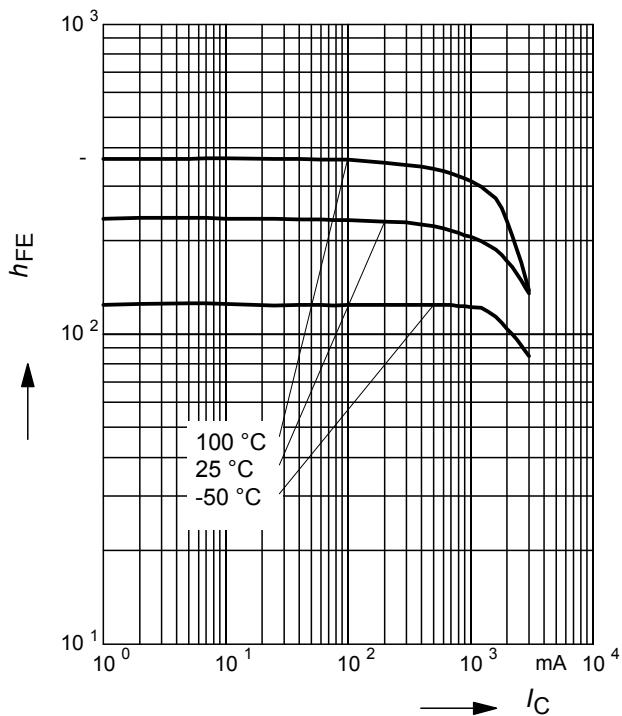
**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 10 \text{ mA}, I_B = 0$ , BDP948	$V_{(\text{BR})\text{CEO}}$	45	-	-	V
$I_C = 10 \text{ mA}, I_B = 0$ , BDP950		60	-	-	
$I_C = 10 \text{ mA}, I_B = 0$ , BDP954		100	-	-	
Collector-base breakdown voltage $I_C = 100 \mu\text{A}, I_E = 0$ , BDP948	$V_{(\text{BR})\text{CBO}}$	45	-	-	
$I_C = 100 \mu\text{A}, I_E = 0$ , BDP950		60	-	-	
$I_C = 100 \mu\text{A}, I_E = 0$ , BDP954		120	-	-	
Emitter-base breakdown voltage $I_E = 10 \mu\text{A}, I_C = 0$	$V_{(\text{BR})\text{EBO}}$	5	-	-	
Collector-base cutoff current $V_{CB} = 45 \text{ V}, I_E = 0$	$I_{\text{CBO}}$	-	-	0.1	$\mu\text{A}$
$V_{CB} = 45 \text{ V}, I_E = 0, T_A = 150^\circ\text{C}$		-	-	20	
Emitter-base cutoff current $V_{EB} = 4 \text{ V}, I_C = 0$	$I_{\text{EBO}}$	-	-	100	nA
DC current gain <sup>1)</sup> $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}$	$h_{\text{FE}}$	25	-	-	-
$I_C = 500 \text{ mA}, V_{CE} = 1 \text{ V}$		85	-	475	
$I_C = 1 \text{ A}, V_{CE} = 2 \text{ V}$ BDP948,BDP950		50	-	-	
BDP954		15	-	-	
$I_C = 1 \text{ A}, V_{CE} = 2 \text{ V}$					
Collector-emitter saturation voltage <sup>1)</sup> $I_C = 2 \text{ A}, I_B = 0.2 \text{ A}$	$V_{\text{CEsat}}$	-	-	0.5	V
Base emitter saturation voltage <sup>1)</sup> $I_C = 2 \text{ A}, I_B = 0.2 \text{ A}$	$V_{\text{BEsat}}$	-	-	1.3	
<b>AC Characteristics</b>					
Transition frequency $I_C = 50 \text{ mA}, V_{CE} = 10 \text{ V}, f = 100 \text{ MHz}$	$f_T$	-	100	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 100 \text{ MHz}$	$C_{\text{cb}}$	-	40	-	pF

<sup>1</sup>Pulse test:  $t < 300\mu\text{s}$ ;  $D < 2\%$

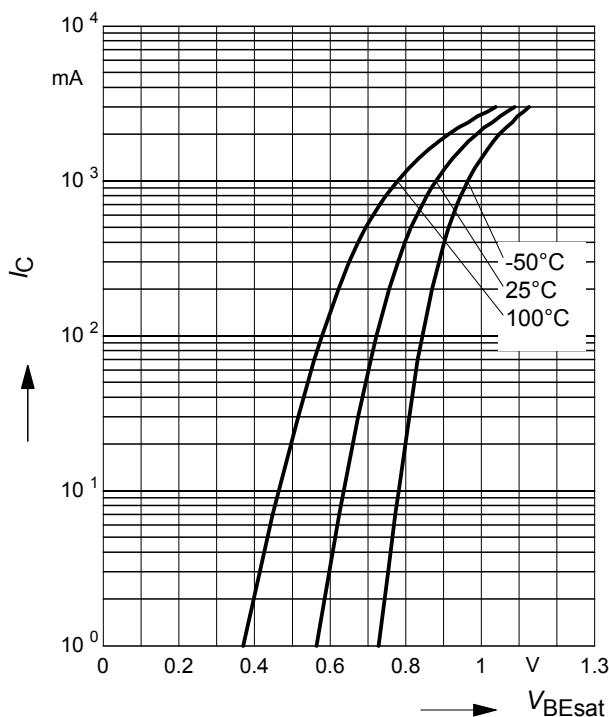
**DC current gain  $h_{FE} = f(I_C)$**

$$V_{CE} = 2 \text{ V}$$



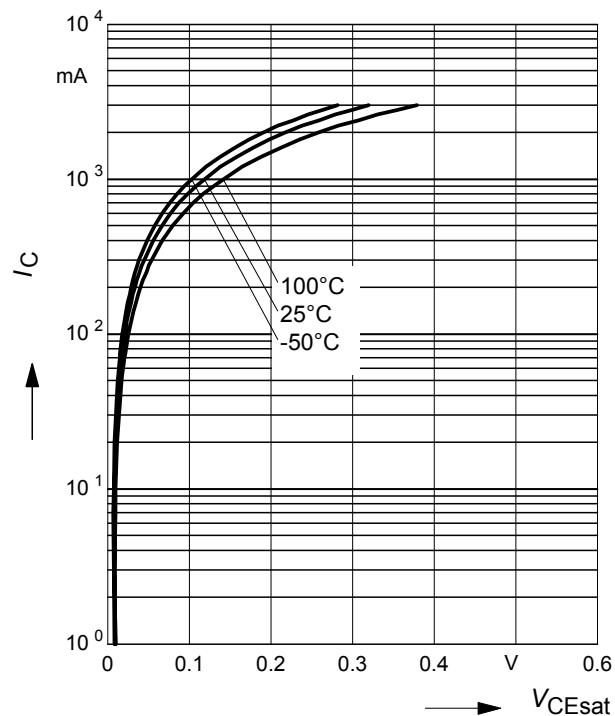
**Base-emitter saturation voltage**

$$I_C = f(V_{BEsat}), h_{FE} = 10$$



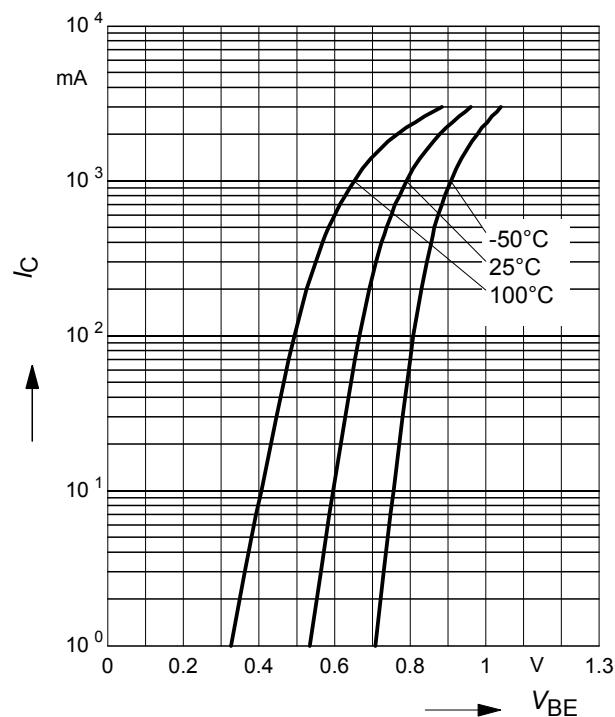
**Collector-emitter saturation voltage**

$$I_C = f(V_{CEsat}), h_{FE} = 10$$

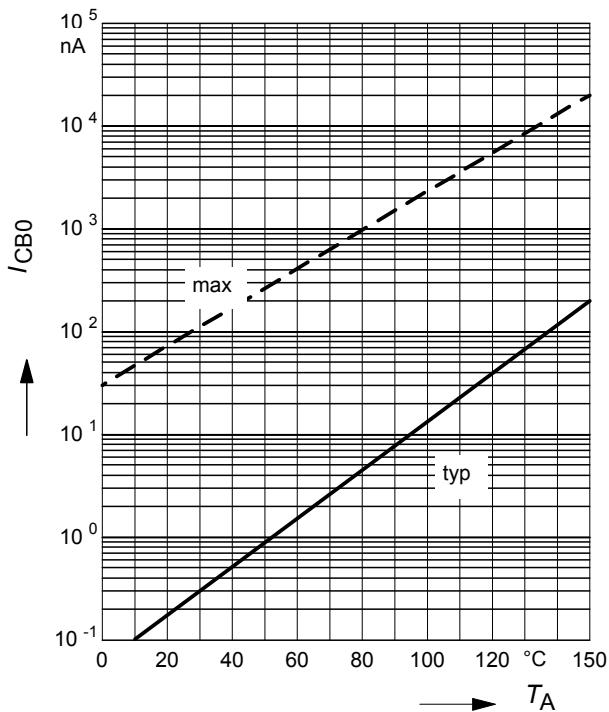


**Collector current  $I_C = f(V_{BE})$**

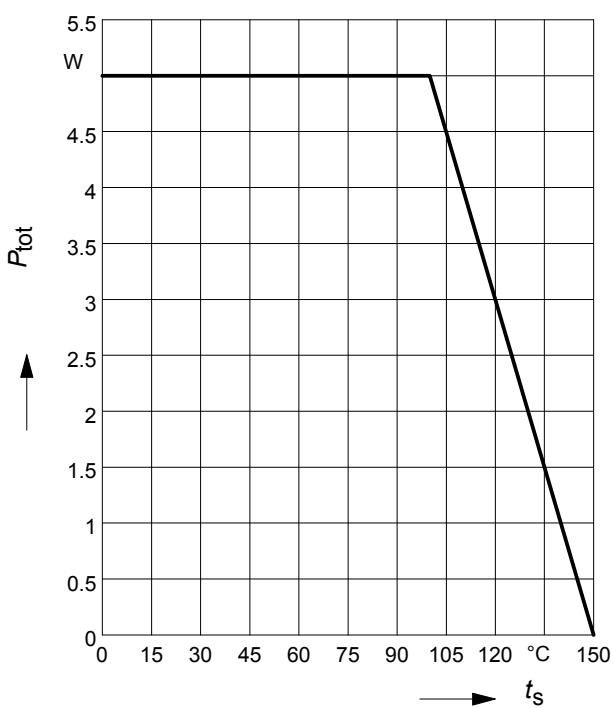
$$V_{CE} = 2 \text{ V}$$



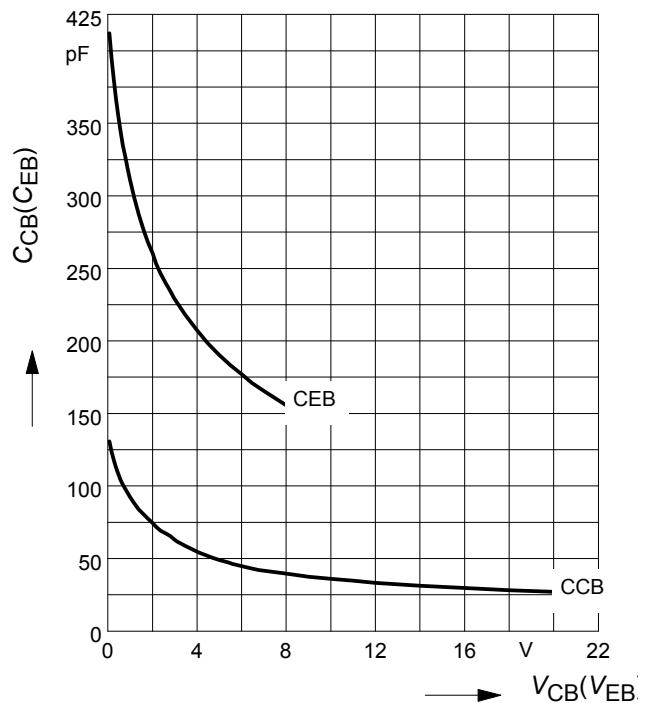
**Collector cutoff current**  $I_{CBO} = f(T_A)$   
 $V_{CB} = 45 \text{ V}$



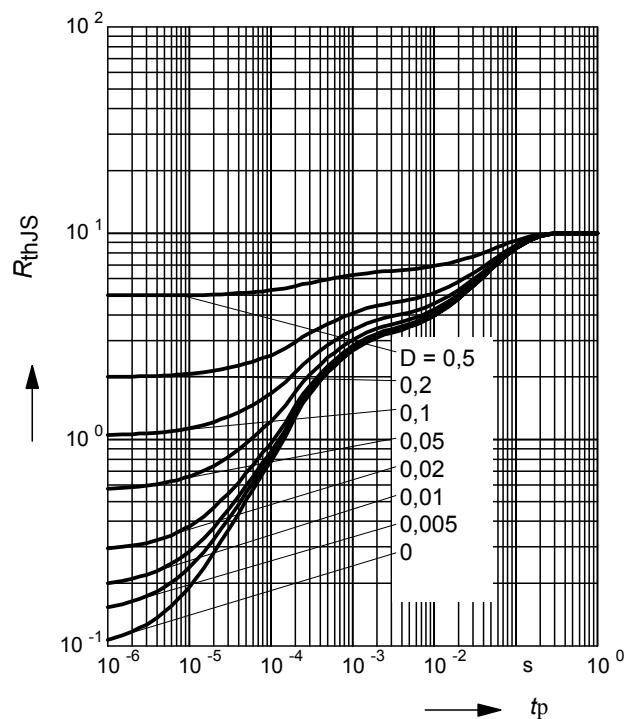
**Total power dissipation**  $P_{\text{tot}} = f(T_S)$



**Collector-base capacitance**  $C_{cb} = f(V_{CB})$   
**Emitter-base capacitance**  $C_{eb} = f(V_{EB})$

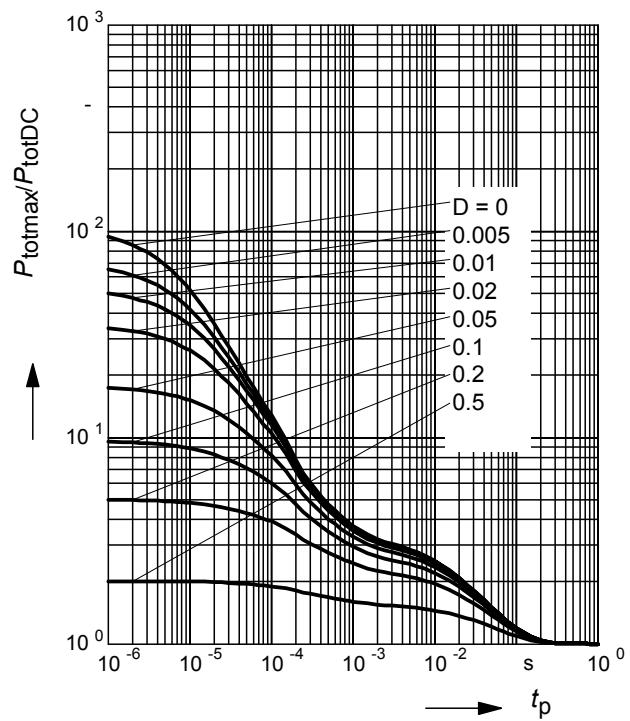


**Permissible Pulse Load**  $R_{\text{thJS}} = f(t_p)$

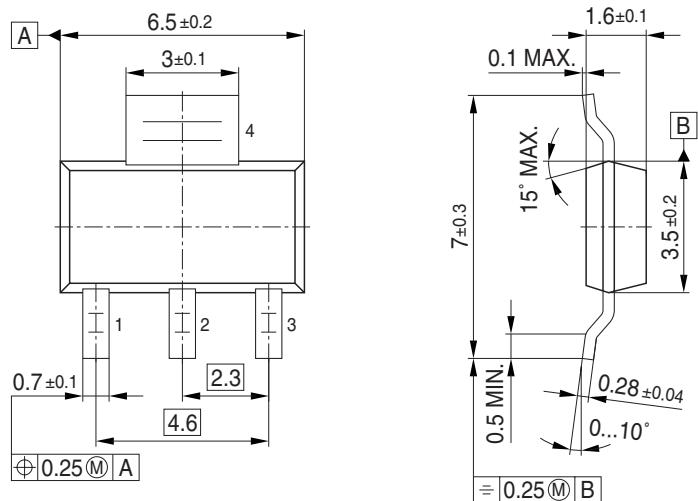


**Permissible Pulse Load**

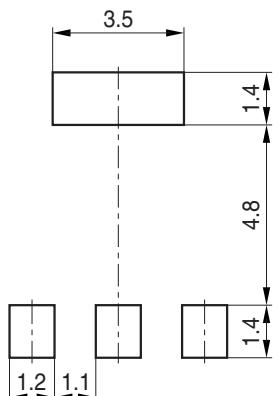
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$$



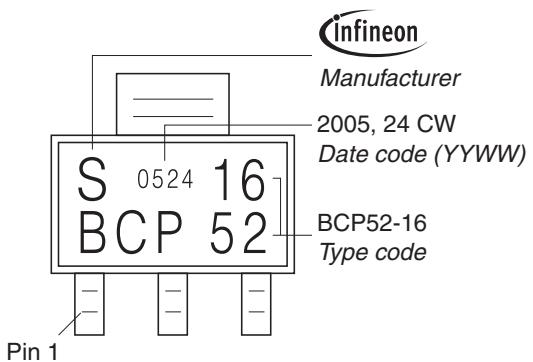
## Package Outline



## Foot Print

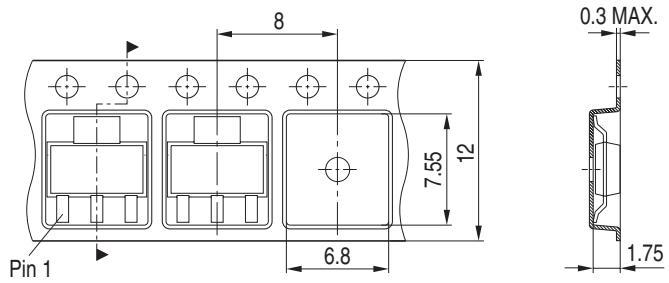


## Marking Layout (Example)



## Packing

Reel ø180 mm = 1.000 Pieces/Reel  
Reel ø330 mm = 4.000 Pieces/Reel



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